



10/785,122

Cafe-
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Hall et al.

Patent No.: 7,116,000 B2

Issued: October 3, 2006

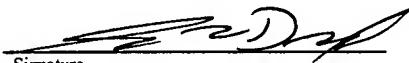
For: UNDERFILLED, ENCAPSULATED
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Attorney Docket No.: 2269-5165.1US

CERTIFICATE OF MAILING

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LETTER MAKING ERRORS OF RECORD

Certificate

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of Correction

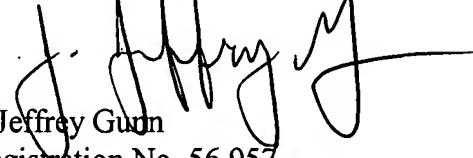
Sir:

Please make the following errors of record in the file history of the above-referenced
Letters Patent:

In the specification:

COLUMN 6,	LINE 51,	change "adhesive element 130" to --adhesive elements 130--
COLUMN 6,	LINE 57,	after "materials" and before "T693-R3001EX-V3" insert --are--
COLUMN 6,	LINE 64,	after "than" and before "particle" insert -- the--
COLUMN 6,	LINE 66,	after "enhancing" and before "flow" insert --the--
COLUMN 7,	LINE 27,	delete "the"; and change "substrate 110" to -- substrates--
COLUMN 8,	LINE 46,	change "provides" to --provide--
COLUMN 8,	LINES 47-48,	change "adhesive element 130" to --adhesive elements 130--
COLUMN 9,	LINE 60,	delete "a" at the beginning of line

Respectfully submitted,



J. Jeffrey Gunn
Registration No. 56,957
Attorney for Applicants
TRASKBRITT, PC
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: August 30, 2007

JJG/df/slm

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